TE0705 TRM

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Overview

The Trenz Electronic TE0705 carrier board provides functionality for testing, evaluation and development purposes of company's 4 x 5 cm SoMs (System on Module). The carrier board is equipped with a broad range of various components and connectors for different configuration setups and needs. On-module functional components and multipurpose I/Os of the SoM's PL and PS logic are connected via board-to-board connectors to the carrier board components and connectors for easy user access.

See "4 x 5 cm carriers" page for more information about supported 4 x 5 cm SoMs.

Block Diagram

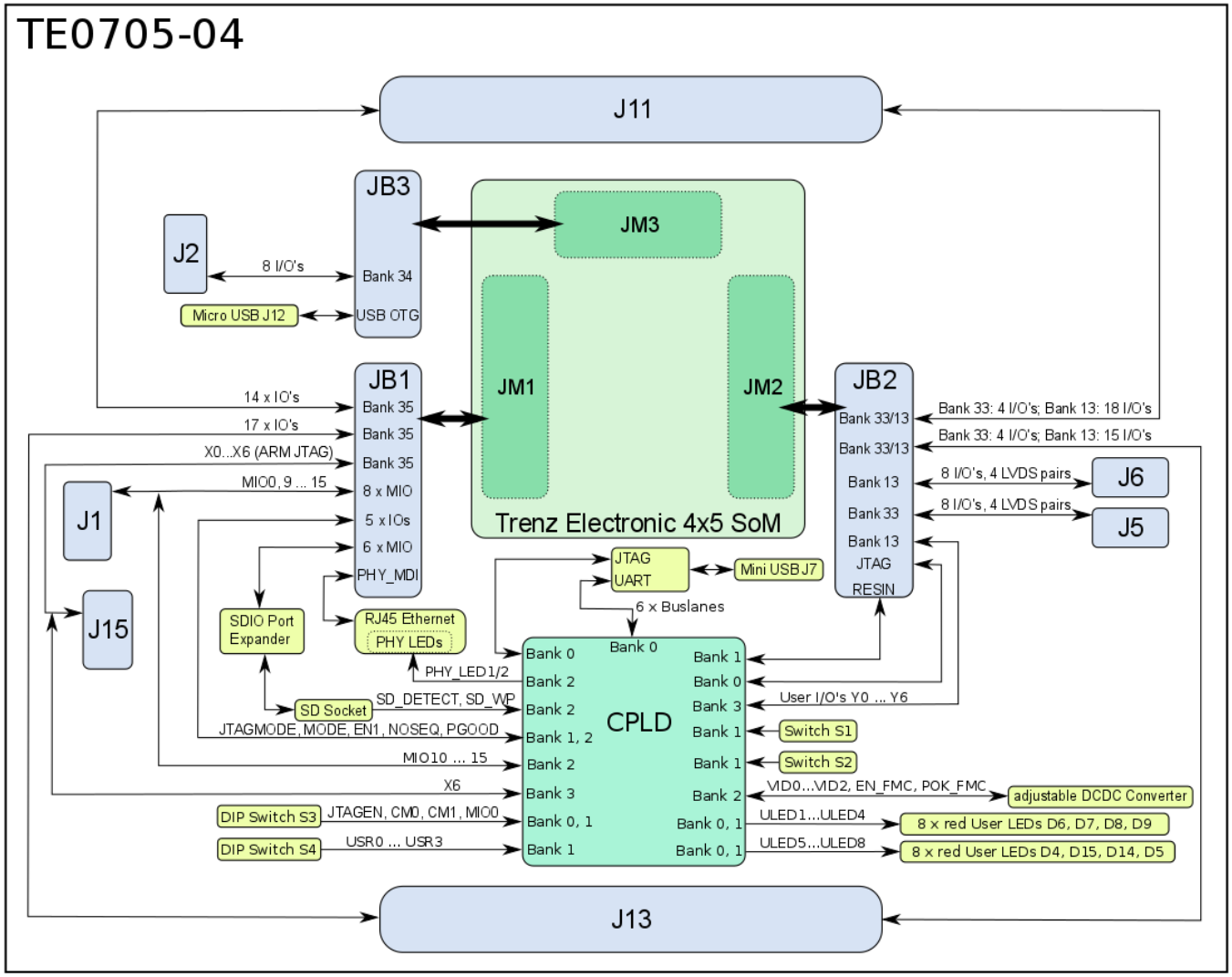


Figure 1: TE0705-04 Block Diagram.

Main Components

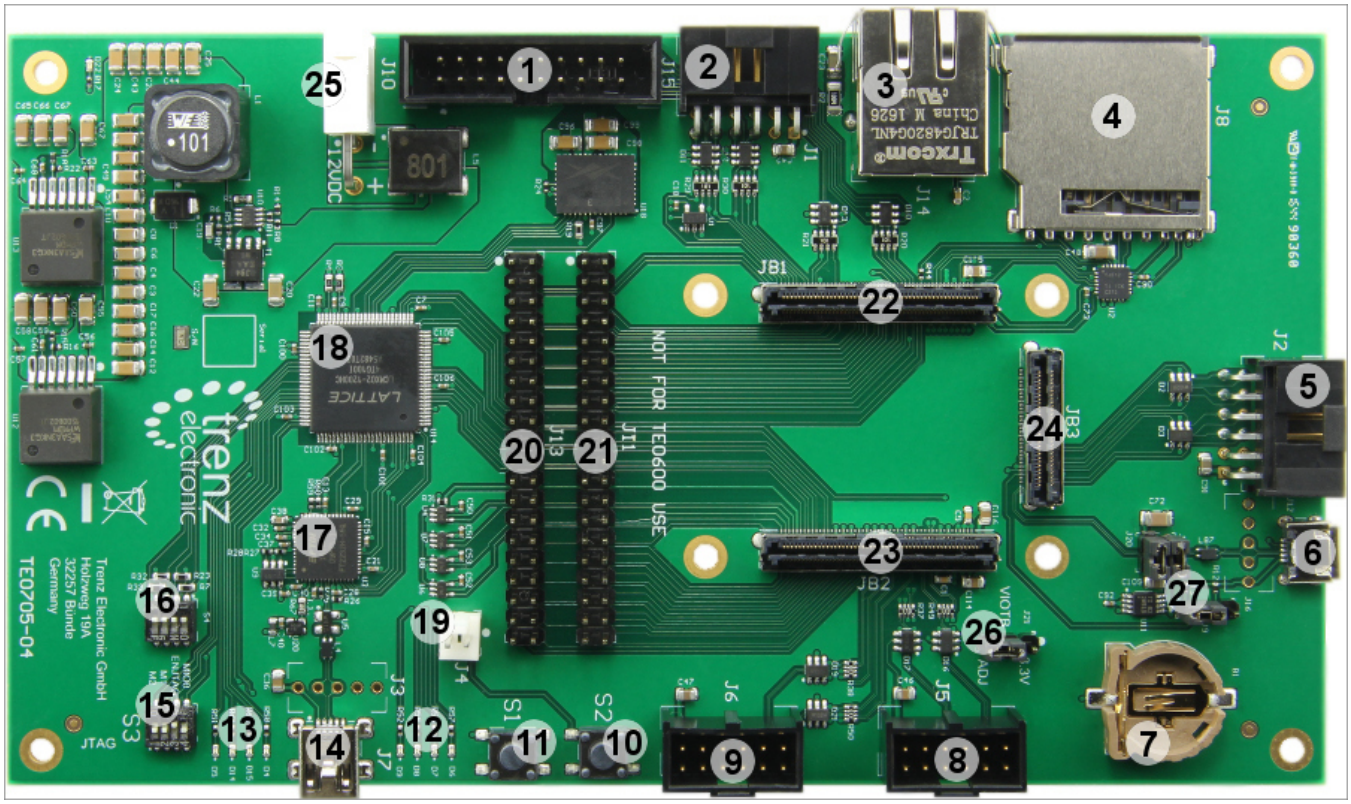


Figure 2: 4 x 5 SoM carrier board TE0705-04.

1. ARM JTAG Connector (DS-5 D-Stream) J15 - functionality depends on connected module
2. 12-pin Molex 90130-3212 header socket J1 (right angle, max. VCCIO voltage 3.3V)
3. RJ45 GbE Connector
4. SD Card Socket - Zynq SDIO0 bootable SD port
5. 12-pin Molex 90130-3212 header socket (right angle) J2
6. Micro USB Connector J12 (Device, Host or OTG Modes)
7. Battery holder for CR1220 (RTC backup voltage)
8. 12-pin Molex 90130-1212 header socket (vertical) J5
9. 12-pin Molex 90130-1212 header socket (vertical) J6
10. User Push-Button S2 ("RESTART" button by default)
11. User Push-Button S1 ("RESET" button by default)
12. User LEDs D6, D7, D8, D9
13. User LEDs D4, D5, D14, D15
14. Mini USB Connector (USB JTAG and UART Interface) J7
15. User 4-bit DIP-Switch S3
16. User 4-bit DIP-Switch S4
17. FTDI FT2232H USB 2.0 High Speed to UART/FIFO
18. Lattice Semiconductor MachXO2 1200HC System Controller CPLD
19. Jumper J4 to fix user button S2 to switched state
20. 40-Pin-Header J13 for access to PL IO-bank-pins
21. 40-Pin-Header J11 for access to PL IO-bank-pins
22. Samtec Razor Beam™ LSHM-150 B2B connector JB1
23. Samtec Razor Beam™ LSHM-150 B2B connector JB2
24. Samtec Razor Beam™ LSHM-130 B2B connector JB3
25. Mini-Fit JR Header 2Pol for 12V power supply J10
26. Jumper J21 to select supply voltage of VIOTB
27. Jumper J9, J19, J20 to select supply voltage of USB-VBUS

Key Features

- Overvoltage, undervoltage and reverse supply protection controller
- Mini-Fit JR Header 2Pol for 12V power supply
- On-board System Controller CPLD (Lattice MachXO2 1200HC), programmable via Mini-USB JTAG interface J7
- SoM can be programmed through System Controller CPLD via Mini-USB JTAG interface J7
- RJ45 Gigabit Ethernet MagJack with 2 integrated LEDs
- 2 x 40-pin headers J11 and J13 for access to module's PL IO bank pins
- USB JTAG/UART interface (FTDI FT2232H) with Mini-USB connector J7
- 8 x user LEDs (red) routed to System Controller CPLD
- 2 x user-push buttons routed to System Controller CPLD. By default (depending on CPLD firmware) configured as system "RESET" and "RESTART" buttons
- 2 x 4-bit DIP-switch for baseboard configuration
- 2 x 12-pin IDC header socket (vertical) J5, J6 for accessing module's PL IO bank pins, can be used as LVDS pairs
- 2 x 12-pin IDC header socket (right angle) J1 and J2 for accessing module's PL IO bank pins or PS MIO0 bank pins (if used with Zynq module)
- 2 x 50-pin IDC header J11, J13 for accessing module's PL IO bank pins
- Micro SD card socket with card detect switch, can be used for system booting
- Micro-USB interface (J12) connected to SoM's USB transceiver (Device, Host or OTG modes)
- Trenz Electronic 4 x 5 cm module connectors (3 x Samtec LSHM series)

Interfaces and Pins

Micro SD Card Socket

Micro SD card socket is connected to the B2B connector through a Texas Instruments TXS02612 SDIO Port Expander for voltage translation. The Micro SD card has 3.3V signal voltage level while Xilinx Zynq MIO bank uses 1.8V for VCCIO.

Dual Channel USB to UART/FIFO

The TE0705 carrier board has on-board USB 2.0 high-speed to UART/FIFO IC FT2232H from FTDI. Channel A can be used as JTAG Interface (MPSSE) to program the System Controller CPLD. Channel B can be used as UART Interface routed to CPLD. There are also 6 additional bus-lanes available for user-specific use.

There is also a 256-byte serial EEPROM connected to the FT2232H chip pre-programmed with license code to support Xilinx programming tools.

> Do not access the FT2232H EEPROM using FTDI programming tools, doing so will erase normally invisible user EEPROM content and invalidate stored Xilinx JTAG license. Without this license the on-board JTAG will not be accessible any more with any Xilinx tools. Software tools from FTDI website do not warn or ask for confirmation before erasing user EEPROM content.

USB Interface

The TE0705 carrier board has two USB connectors:

- J7 as mini-USB connector wired to on-board FTDI FT2232H chip.
- J12 as micro-USB connector wired to B2B connector JB3 (usually there is an USB transceiver on the SoM).

JTAG Interface

JTAG access to the on-board System Controller CPLD and SoM is provided via mini-USB JTAG interface J7 (FTDI FT2232H) and controlled by DIP switch S3-3.

S3-3 Position	Description
ON	Enable JTAG interface for SoM via B2B connector JB2.

OFF	Enable JTAG interface for on-board System Controller CPLD.

LEDs

There are eight LEDs (D6, D7, D8, D9, D4, D5, D14, D15) available to the user. All LEDs are red colored and mapped to the on-board System Controller CPLD. Their functions are programmable and depend on the firmware of the System Controller CPLD. For detailed information, please refer to the documentation of the TE0705 System Controller CPLD.

Green LED D22 is to indicate availability of the 3.3V power supply to the TE0705 carrier board.

4-bit DIP-switch S3

Switch	Functionality
S3-1	CM1: Mode pin 1 (routed to System Controller CPLD).
S3-2	CM0: Mode pin 0 (routed to System Controller CPLD).
S3-3	JTAGEN: Set to ON for normal JTAG operation. Must be moved to OFF position for TE0705 System Controller CPLD update only.
S3-4	MIO0: Set MIO0 pin (on MIO0-Bank) on Zynq modules, else active-low user IO pin.

Table 1: Configuration of DIP-switch S3.

4-bit DIP-switch S4

Additionally there is a 4-bit DIP-switch S4 available routed to the System Controller CPLD which function is user configurable via custom CPLD firmware. Please refer to the TE0705 System Controller CPLD documentation for more information.

All switch S4 pins are connected to 3.3V pull-up resistors in OFF position.

User Push-Buttons

On the TE0705 Carrier Board there are two push buttons (S1 and S2) and are routed to the System Controller CPLD and available to the user. The default mapping of the push buttons is as follows:

Name	Default Mapping:
S1	If S1 is pushed, the active-low RESet IN (RESIN) signal will be asserted. **Note**: This reset can also be forced by the FTDI USB to JTAG interface.
S2	If S2 is pushed, the active-high Power ON (PON) signal (that is internally pulled-up) will be deasserted, which can be considered as a "RESTART" button to switch *off* (push button) and *on* (release button) all on-module power supplies (except 3.3VIN). **Note**: The capability of the switch to be enabled the first time will become active shortly after *Power on Reset* (POR). ⓘ The active-high PON signal is directly mapped to the active-high EN1 signal which is routed to the module's System Controller CPLD (e.g., on the TE0720) and directly used (after deglitching) as a mandatory active-high enable signal to the power FET switch (3.3VIN -> 3.3V) as well as for the DC-DC converters (VIN -> 1.0V, 1.5V, 1.8V). By closing jumper J4, the PON signal will be permanently deasserted, hence the power FET switch and the DC-DC converters on module will be disabled.

Table 2: Description of the standard functionality of user push-buttons S1 and S2.

The functionality of the push buttons depends on the CPLD firmware. For detailed information of the function of the push buttons, please refer to the documentation of the TE0705 System Controller CPLD.

Ethernet

The TE0705 Carrier Board has a RJ45 Gigabit Ethernet MagJack (J14) with two LEDs.

On-board Ethernet MagJack J14 pins are routed to B2B connector JB1 via MDI. The center tap of the Magnetics is not connected to module's B2B connector.

PHY LEDs are not connected directly to the module's B2B connectors as the TE 4 x 5 cm modules have no dedicated PHY LED pins assigned. PHY LEDs are connected to the TE0705 System Controller CPLD, that can route those LEDs to some the module's IO Pins. In that case, the CPLD has to map the PHY LEDs to corresponding module's IO pins.

See documentation of the TE0705 System Controller CPLD to get information of the function of the PHY LEDs.

IDC header sockets J5 and J6

On the TE0705 there two IDC header available for access to SoM's PL IO-bank pins

J5 and J6 sockets signal routing is done as differential pairs for pins 1-3, 2-4, 5-7, 6-8, hence 4 LVDS pairs are possible on this sockets. The differential pairs are operable with max. VCCIO voltage VIOTB.

IDC header socket J1

IDC header J1 provides access to SoM's PL IO-bank pins, whereby 6 pins (net name: 'MIO10' to 'MIO15') of this header are also routed to the System Controller CPLD.

If Zynq module is mounted on the TE0705 carrier board, the pins of this header are routed to the corresponding pins of the PS logic of the SoM: MIO0-bank pins MIO0, MIO9-MIO15 are accessible on header J1 and operable with max. VCCIO voltage 3.3V.

An exception here is the 'MIO12'-pin, which is buffered with a Schmitt-Trigger buffer with a hysteresis of 5.0V.

'MIO12'-pin, is buffered with a Schmitt-Trigger buffer with a hysteresis of 5.0V.

IDC header socket J2

12-pin header J2 provides access to SoM's PL IO-bank pins routed to B2B-connector JB3. Operable with fixed (3.3V) or adjustable VCCIO voltage VIOTB (Single ended IOs, not usable as LVDS pairs).

40-pin headers J11 and J13

40-pin header J11 and J13 provide access to SoM's PL IO-bank pins routed to B2B-connectors JB1 and JB2. Operable with fixed (3.3V) or adjustable VCCIO voltage VIOTB (Single ended IOs, not usable as LVDS pairs).

Power and Power-On Sequence

Power Supply

Single 12V power supply with minimum current capability of 3A is recommended to operate the board.

Power-On Sequence

All on-board voltages of the carrier board will be powered up simultaneously when single power-supply with a nominal voltage of 12V is connected to the power-jack J10.

The PL IO-bank supply voltage FMC_VADJ is available after the output of the 5.0V DC-DC converter is active and the EN_FMC pin of the System Controller CPLD is asserted.

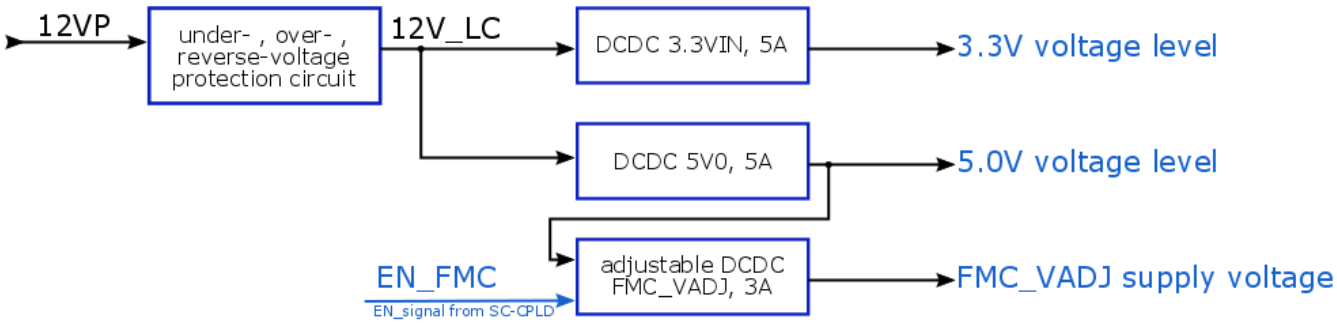


Figure 3: Power-On sequence diagram.

Configuring VCCIO

On the TE0705 carrier board different VCCIO configurations are selectable by jumper J21 and DIP-switch S3.

The purpose of the jumper and the DIP-switch S3 of the Carrier Board will be explained in the following sections.

VCCIO Voltage Level DIP-Switch S3

With jumper J21, user can select between two different power sources for SoM PL IO banks supply voltage VIOTB. If set to position 1-2, fixed 3.3V is selected as VIOTB source. If set to position 2-3, FMC_VADJ is selected as VIOTB source. Voltage level of FMC_VADJ depends on the settings of DIP-switch S3, see table below:

J21 Position	S3-1 (CM1)	S3-2 (CM0)	FMC_VADJ Voltage	VIOTB Voltage	Notes
1-2	-	-	-	3.3V	
2-3	OFF	OFF	1.8V	1.8V	
2-3	ON	OFF	2.5V	2.5V	
2-3	OFF	ON	3.3V	3.3V	
2-3	ON	ON	1.8V	1.8V	This setting also enables JTAG access to the System Controller CPLD on the SoM via B2B connector JB2.

Table 3: Jumper J21 and DIP-switch S3 settings for VIOTB voltage configuration.

Note: Exact function of the S3-1 and S3-2 switches depend on the TE0705 System Controller CPLD firmware. For more detailed information, refer to the documentation of the TE0705 System Controller CPLD.

Configuring Power Supply of the Micro USB Connector (Device, Host or OTG Modes)

The TE0705 carrier board can be configured as USB host device. Hence, it must provide from 5.25V to 4.75V to the board side of the downstream connection (micro USB port J12). To provide sufficient power, a TPS2051 power distribution switch is located on the carrier board in between the 5V power supply and the Vbus signal of the USB downstream port interface. If the output load exceeds the current-limit threshold, the TPS2051 limits the output current and pulls the over-current logic output (OC_n) low, which is routed to the on-board CPLD. The TPS2051 is put into operation by setting J19 CLOSED. J20 provides an extra 100µF decoupling capacitor (in addition to 10µF) to further stabilize the output signal. Moreover, a series terminating resistor of either 1K (J9: **1-2**, 3) or 10K (J9: 1, **2-3**) is selectable on the "USB-VBUS" signal. Both signals, USB-VBUS and VBUS_V_EN (that enables the TPS2051 on "high") are routed (as well as the corresponding D+/- data lines) via the on-board connector directly to the USB 2.0 high-speed transceiver PHY on the mounted SoM. In summary, the default jumper settings are the following: J9: **1-2**, 3 (1K series terminating resistor); J19: CLOSED (TPS2051 in operation); J20: CLOSED (100 µF added).

Additionally, the TE0705 carrier board is equipped with a second mini USB port J7 that is connected to a "USB to multi-purpose UART/FIFO IC" from FTDI (FT2232H) and provides a USB-to-JTAG interface between a host PC and the TE0705 carrier board and the mounted SoM, respectively. Because it acts as a USB function device, no power switch is required (and only a ESD protection must be provided) in this case.

Summary of VCCIO Configuration

All B2B VCCIO supply voltages to the 4 x 5 SoM (VCCIOA, VCCIOB, VCCIOC and VCCIOD, see 4 x 5 Module Integration Guide) are connected to the 3.3 V VIOTB, which is either fixed to 3.3V (J21: **1-2**, 3) or selectable with the adjustable supply-voltage FMC_VADJ (J21: 1, **2-3**). The supply-voltages have following pin assignments on B2B-connectors:

baseboard supply-voltages	baseboard B2B connector-pins	standard assignment of PL IO-bank supply-voltages on TE 4x5 module's B2B connectors	baseboard voltages and signals connected with
VIOTB	JB1-10, JB1-12, JB2-2, JB2-4, JB2-6, JB2-8, JB2-10	VCCIOA (JM1-9, JM1-11), VCCIOB (JM2-1, JM2-3), VCCIOC (JM2-5), VCCIOD (JM2-7, JM2-9)	VCCIO3 (System Controller CPLD pin 5, 11, 23), J15 VTREF, J11, J13, J2, J5 and J6 VCCIO

Table 4: baseboard supply-voltage VIOTB.

> **Note**: The corresponding PL IO-voltage supply voltages of the 4 x 5 SoM to the selectable baseboard voltage VIOTB are depending on the mounted 4 x 5 SoM and varying in order of the used model.
>
> Refer to SoM's schematic to get information about the specific pin assignment on module's B2B-connectors regarding PL IO-bank supply voltages and to the 4 x 5 Module integration Guide for VCCIO voltage options.

Following table describes how to configure the baseboard supply-voltages by jumpers:

baseboard supply-voltages vs voltage-levels	VIOTB	USB-VBUS
3V3	J21: **1-2**, 3	-
VADJ	J21: 1, **2-3**	-
5V0 intern	-	J9: **1-2**, 3 & J19: **1-2** (J20: **1-2**: additional decoupling-capacitor 100 µF)
Vbus extern	-	J9: 1, **2-3** & J19: open

Table 5: Configuration of baseboard supply-voltages via jumpers. Jumper-Notification: 'Jx: **1-2**, 3' means pins 1 and 2 are connected, 3 is open. 'Jx: 1, **2-3**' means pins 2 and 3 are connected, 1 is open.

> Take care of the VCCO voltage ranges of the particular PL IO-banks (HR, HP) of the mounted SoM, otherwise damages may occur to the FPGA. Therefore, refer to the TRM of the mounted SoM to get the specific information of the voltage ranges.
>
> It is recommended to set and measure the PL IO-bank supply-voltages before mounting of TE 4 x 5 module to avoid failures and damages to the functionality of the mounted SoM.

Board to Board Connectors

These connectors are hermaphroditic. Odd pin numbers on the module are connected to even pin numbers on the baseboard and vice versa.

4 x 5 modules use two or three Samtec Razor Beam LSHM connectors on the bottom side.

- 2 x REF-189016-02 (compatible to LSHM-150-04.0-L-DV-A-S-K-TR), (100 pins, "50" per row)
- 1 x REF-189017-02 (compatible to LSHM-130-04.0-L-DV-A-S-K-TR), (60 pins, "30" per row) (depending on module)

Connector Mating height

When using the same type on baseboard, the mating height is 8mm. Other mating heights are possible by using connectors with a different height

Order number	Connector on baseboard	compatible to	Mating height
23836	REF-189016-01	LSHM-150-02.5-L-DV-A-S-K-TR	6.5 mm
	LSHM-150-03.0-L-DV-A-S-K-TR	LSHM-150-03.0-L-DV-A-S-K-TR	7.0 mm
23838	REF-189016-02	LSHM-150-04.0-L-DV-A-S-K-TR	8.0 mm
	LSHM-150-06.0-L-DV-A-S-K-TR	LSHM-150-06.0-L-DV-A-S-K-TR	10.0mm
26125	REF-189017-01	LSHM-130-02.5-L-DV-A-S-K-TR	6.5 mm
	LSHM-130-03.0-L-DV-A-S-K-TR	LSHM-130-03.0-L-DV-A-S-K-TR	7.0 mm
24903	REF-189017-02	LSHM-130-04.0-L-DV-A-S-K-TR	8.0 mm
	LSHM-130-06.0-L-DV-A-S-K-TR	LSHM-130-06.0-L-DV-A-S-K-TR	10.0mm

Connectors.

The module can be manufactured using other connectors upon request.

Connector Speed Ratings

The LSHM connector speed rating depends on the stacking height; please see the following table:

Stacking height	Speed rating
12 mm, Single-Ended	7.5 GHz / 15 Gbps
12 mm, Differential	6.5 GHz / 13 Gbps
5 mm, Single-Ended	11.5 GHz / 23 Gbps
5 mm, Differential	7.0 GHz / 14 Gbps

Speed rating.

Current Rating

Current rating of Samtec Razor Beam™ LSHM B2B connectors is 2.0A per pin (2 adjacent pins powered).

Connector Mechanical Ratings

- Shock: 100G, 6 ms Sine
- Vibration: 7.5G random, 2 hours per axis, 3 axes total

Manufacturer Documentation

File	Modified
PDF File hsc-report_lshm-lshm-05mm_web.pdf High speed test report	07 04, 2016 by Thorsten Trenz
PDF File lshm_dv.pdf LSHM catalog page	07 04, 2016 by Thorsten Trenz
PDF File LSHM-1XX-XX.X-X-DV-A-X-X-TR-FOOTPRINT(1).pdf Recommended layout and stencil drawing	07 04, 2016 by Thorsten Trenz
PDF File LSHM-1XX-XX.X-XX-DV-A-X-X-TR-MKT.pdf Technical drawing	07 04, 2016 by Thorsten Trenz
PDF File REF-189016-01.pdf Technical Drawing	07 04, 2016 by Thorsten Trenz
PDF File REF-189016-02.pdf Technical Drawing	07 04, 2016 by Thorsten Trenz
PDF File REF-189017-01.pdf Technical Drawing	07 04, 2016 by Thorsten Trenz
PDF File REF-189017-02.pdf Technical Drawing	07 04, 2016 by Thorsten Trenz
PDF File TC0923--2523_report_Rev_2_qua.pdf Design qualification test report	07 04, 2016 by Thorsten Trenz
PDF File tc0929--2611_qua(1).pdf Shock and vibration report	07 04, 2016 by Thorsten Trenz

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Technical Specifications

Absolute Maximum Ratings

Parameter	Min	Max	Units	Notes
VIN supply voltage	11.4	12.6	V	12.0V supply voltage ± 5%
Storage temperature	-55	125	°C	Lattice MachX02 family data sheet

Recommended Operating Conditions

Parameter	Min	Max	Units	Notes
VIN supply voltage	11.4	12.6	V	-

Physical Dimensions

- Board size: 170.4 mm × 98 mm. Note that few parts are slightly hanging over the PCB edge, like mini USB jacks (ca. 1.4 mm) and the Ethernet RJ-45 jack (ca 2.2 mm), which determine the total physical dimensions of the carrier board. Please download the assembly diagram for exact numbers.
- Mating height of the module with standard connectors: 8 mm.
- PCB thickness: ca. 1.65 mm.
- Highest part on the PCB is the Ethernet RJ-45 jack (approximately 17 mm). Please download the step model for exact numbers.

All dimensions are given in millimeters.

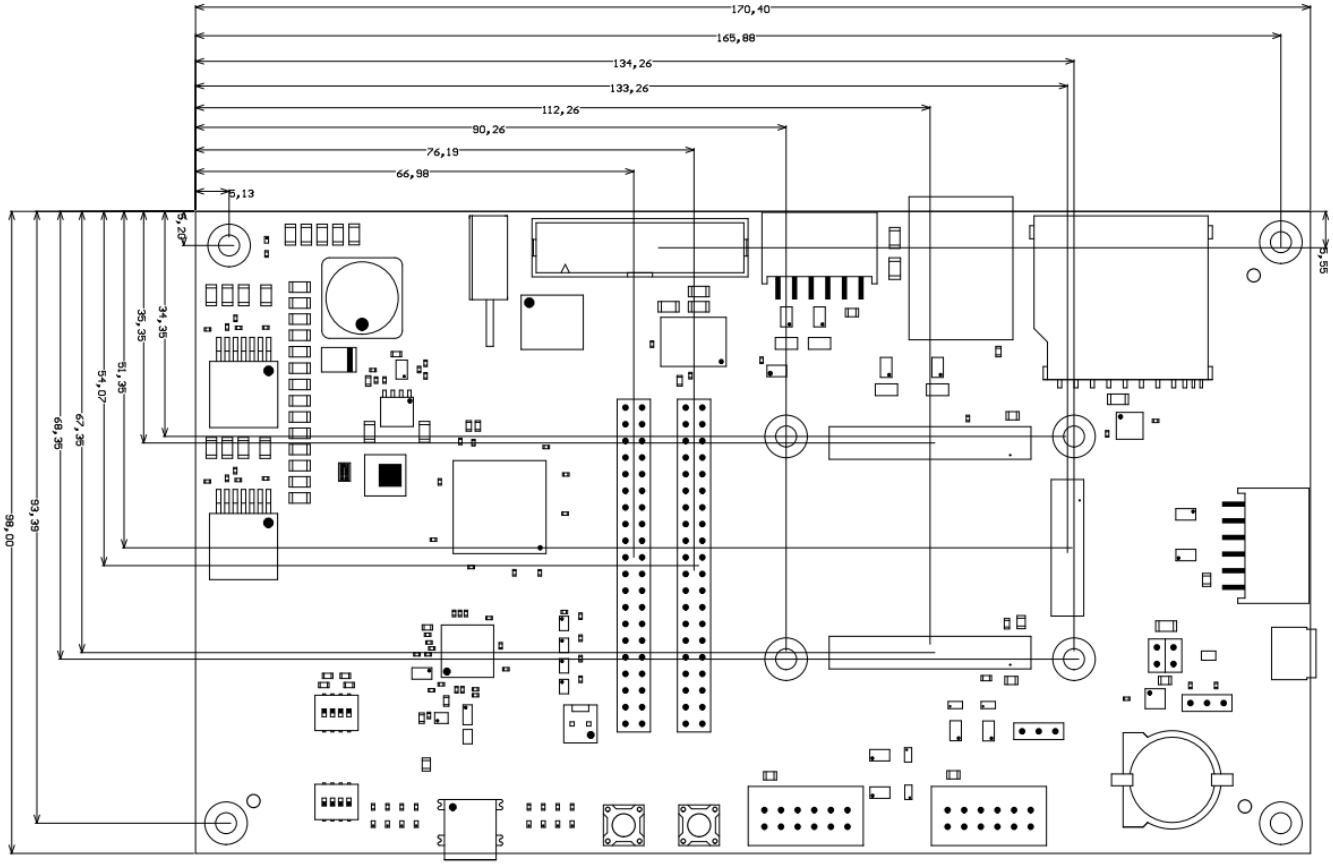


Figure 4: Physical dimensions of the TE0705-04 carrier board.

Operating Temperature Ranges

Commercial grade: 0°C to +70°C.

Board operating temperature range depends also on customer design and cooling solution. Please contact us for options.

Weight

Approximately 110 g - Plain board.

Revision History

Hardware Revision History

Date	Revision	Notes	PCN	Documentation link
2016-10-04	04	-	-	TE0705-04

Figure 5: Hardware revision number.

Hardware revision number is printed on the PCB board next to the model number separated by the dash.



Document Change History

Date	Revision	Contributors	Description

Error rendering macro 'page-info' Ambiguous method overloading for method jdk.proxy244.$Proxy3572#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]	**Error rendering macro 'page-info'** Ambiguous method overloading for method jdk.proxy244.$Proxy3572#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]	**Error rendering macro 'page-info'** Ambiguous method overloading for method jdk.proxy244.$Proxy3572#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]	• correction J10 description
2020-08-19	v.18	John Hartfiel	• correction J15 description
2019-06-27	v.17	John Hartfiel	• typo VADJ DIP settings
2019-03-14	v.16	John Hartfiel	• Add B2B section • Note MIO12
2017-02-08	V.11	Ali Naseri, Jan Kumann	• TRM for TE0705-04

--	all	**Error rendering macro 'page-info'** Ambiguous method overloading for method jdk.proxy244.$Proxy3572#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]	• --

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Please also note our data protection declaration at https://www.trenz-electronic.de/en/Data-protection-Privacy

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Environmental Protection

To confront directly with the responsibility toward the environment, the global community and eventually also oneself. Such a resolution should be integral part not only of everybody's life. Also enterprises shall be conscious of their social responsibility and contribute to the preservation of our common living space. That is why Trenz Electronic invests in the protection of our Environment.

REACH, RoHS and WEEE

REACH

Trenz Electronic is a manufacturer and a distributor of electronic products. It is therefore a so called downstream user in the sense of REACH. The products we supply to you are solely non-chemical products (goods). Moreover and under normal and reasonably foreseeable circumstances of application, the goods supplied to you shall not release any substance. For that, Trenz Electronic is obliged to neither register nor to provide safety data sheet. According to present knowledge and to best of our knowledge, no SVHC (Substances of Very High Concern) on the Candidate List are contained in our products. Furthermore, we will immediately and unsolicited inform our customers in compliance with REACH - Article 33 if any substance present in our goods (above a concentration of 0,1 % weight by weight) will be classified as SVHC by the European Chemicals Agency (ECHA).

RoHS

Trenz Electronic GmbH herewith declares that all its products are developed, manufactured and distributed RoHS compliant.

WEEE

Information for users within the European Union in accordance with Directive 2002/96/EC of the European Parliament and of the Council of 27 January 2003 on waste electrical and electronic equipment (WEEE).

Users of electrical and electronic equipment in private households are required not to dispose of waste electrical and electronic equipment as unsorted municipal waste and to collect such waste electrical and electronic equipment separately. By the 13 August 2005, Member States shall have ensured that systems are set up allowing final holders and distributors to return waste electrical and electronic equipment at least free of charge. Member States shall ensure the availability and accessibility of the necessary collection facilities. Separate collection is the precondition to ensure specific treatment and recycling of waste electrical and electronic equipment and is necessary to achieve the chosen level of protection of human health and the environment in the European Union. Consumers have to actively contribute to the success of such collection and the return of waste electrical and electronic equipment. Presence of hazardous substances in electrical and electronic equipment results in potential effects on the environment and human health. The symbol consisting of the crossed-out wheeled bin indicates separate collection for waste electrical and electronic equipment.

Trenz Electronic is registered under WEEE-Reg.-Nr. DE97922676.

Error rendering macro 'page-info'

Ambiguous method overloading for method jdk.proxy244.$Proxy3572#hasContentLevelPermission. Cannot resolve which method to invoke for [null, class java.lang.String, class com.atlassian.confluence.pages.Page] due to overlapping prototypes between: [interface com.atlassian.confluence.user.ConfluenceUser, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject] [interface com.atlassian.user.User, class java.lang.String, class com.atlassian.confluence.core.ContentEntityObject]